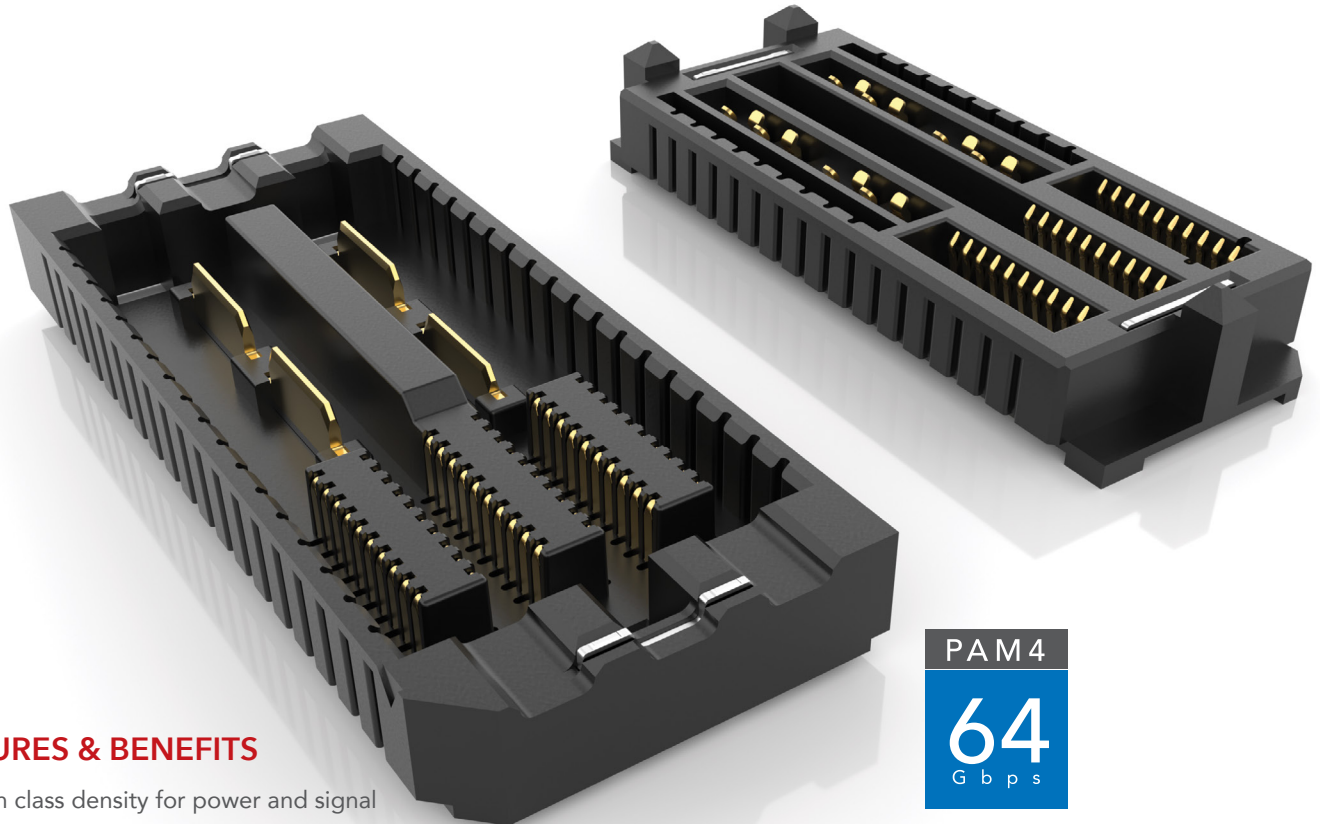


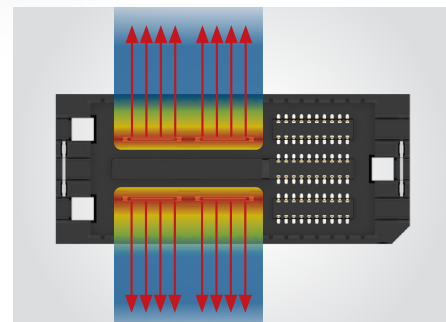
# ACCELERATE<sup>®</sup>mP

## HIGH-DENSITY, HIGH-SPEED POWER/SIGNAL ARRAYS



### FEATURES & BENEFITS

- Best in class density for power and signal
- Rotated power blades improve performance and simplify breakout region (BOR)
- Open-pin-field design for routing and grounding flexibility
- Low profile 5 mm stack height; up to 16 mm in development
- Up to 8 power and 240 signal positions; additional position counts in development
- 0.635 mm signal pitch
- Supports 64 Gbps PAM4 (32 Gbps NRZ) applications
- PCIe<sup>®</sup> 6.0/CXL<sup>®</sup> 3.1 capable
- Weld tabs included for a secure connection to the board
- Polarized guide posts for blind mating
- Optional alignment pins



Blades rotated 90° have equal access to heat escape for uniform cooling, increased current capacity and reduced crowding

### KEY SPECIFICATIONS (UDM6/UDF6)

PITCH	STACK HEIGHTS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
0.635 mm (Signal) 6.00 mm (Power)	5 mm	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	15 A per power pin	200 VAC/ 283 VDC	Yes

PCI-SIG<sup>®</sup>, PCI Express<sup>®</sup> and the PCIe<sup>®</sup> design marks are register trademarks and/or service marks of PCI-SIG.

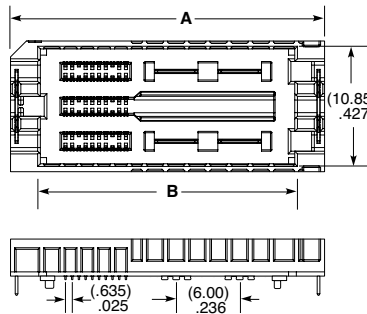
**(0.635 mm) .025" PITCH • UDM6/UDF6 SERIES**

UDM6	NO. OF SIGNAL POSITIONS	NO. OF POWER POSITIONS	LEAD STYLE	PLATING OPTION	OPTION	WELD TAB	"X"R
	-10, -40 (Per Row)	-2, -4 (Per Row)	-01.5 = 1.5 mm	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on tail  -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on tail  -STL = 30 μ" (0.76 μm) Gold on contact area, Tin/Lead on solder tail	(Leave blank for no alignment pin)  -A = Alignment Pin	-TH = Through-Hole	-TR = Tape & Reel  -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

**UDM6**

Board Mates:  
UDF6

Standoffs:  
GPSO



NO. OF SIGNAL PER ROW	NO. OF POWER PER ROW	A	B
-010	-2	(29.68) 1.168	(24.42) .961
-040	-4	(60.73) 2.391	(55.47) 2.184

**UDM6-10-2-01.5-X-A-TH-XR**  
(Some center features removed for clarity)

**Notes:**  
Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: [samtec.com?UDM6](http://samtec.com?UDM6)

UDF6	NO. OF SIGNAL POSITIONS	NO. OF POWER POSITIONS	LEAD STYLE	PLATING OPTION	OPTION	WELD TAB	"X"R
	-10, -40 (Per Row)	-2, -4 (Per Row)	-03.5 = 3.5 mm	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on tail  -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on tail  -STL = 30 μ" (0.76 μm) Gold on contact area, Tin/Lead on solder tail	(Leave blank for no alignment pin)  -A = Alignment Pin	-TH = Through-Hole	-TR = Tape & Reel  -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

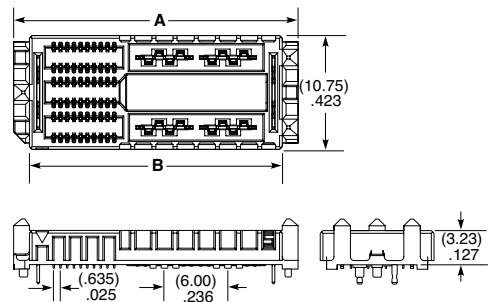
**UDF6**

Board Mates:  
UDM6

Standoffs:  
GPSO



NO. OF SIGNAL PER ROW	NO. OF POWER PER ROW	A	B
-010	-2	(26.88) 1.058	(23.90) .941
-040	-4	(57.93) 2.281	(54.95) 2.163



**UDF6-10-2-03.5-X-A-TH-XR**  
(Some center features removed for clarity)

**Notes:**  
Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: [samtec.com?UDF6](http://samtec.com?UDF6)